

DESCRIPTION

This 16Mx1 Fast Page Mode DRAM family is fabricated using Samsung's advanced CMOS process to realize high band-width, low power consumption and high reliability. It may be used as main memory unit for high level computer and microcomputer.

- **Part Identification**

- **Active Power Dissipation**

Speed	3.3V	5V
-5	324	495
-6	288	440

- Refresh Cycles

Part NO.	V _{CC}	Refresh cycle	Refresh period	
			Normal	L-ver
C16000C	5V	4K	64ms	128ms
V16000C	3.3V			

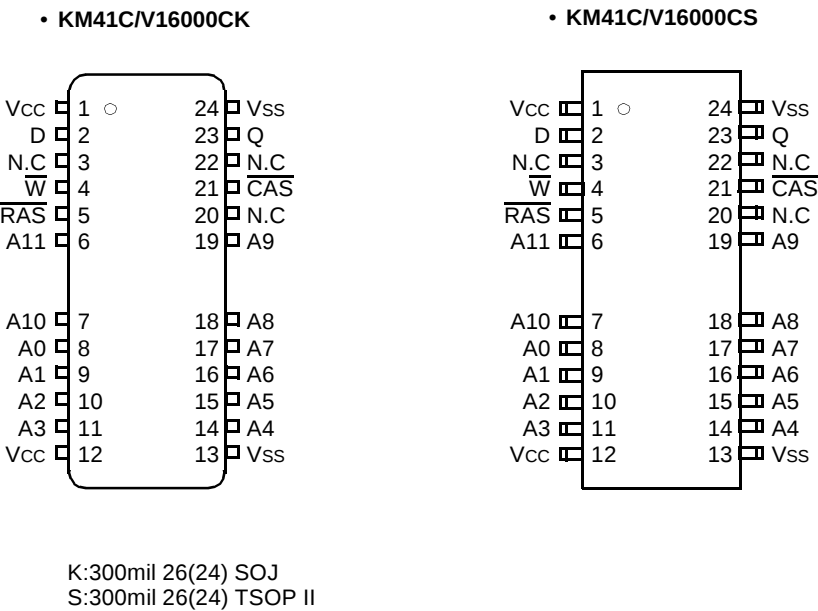
- **Performance Range**

Speed	t _{RAC}	t _{CAC}	t _{RC}	t _{PC}	Remark
-5	50ns	13ns	90ns	35ns	5V/3.3V
-6	60ns	15ns	110ns	40ns	5V/3.3V

The block diagram illustrates the internal architecture of a memory system. At the top left, control signals $\overline{\text{RAS}}$, $\overline{\text{CAS}}$, and $\overline{\text{W}}$ are inputs to the 'Control Clocks' block. A 'VBB Generator' block is connected to V_{CC} and V_{SS} and provides a common clock signal to the 'Refresh Timer', 'Refresh Control', and 'Row Decoder'. The 'Refresh Timer' and 'Refresh Control' are interconnected, with the 'Refresh Control' also receiving input from the 'Refresh Counter'. The 'Refresh Counter' is clocked by the 'Control Clocks' and outputs to the 'Row Address Buffer'. The 'Row Address Buffer' and 'Col. Address Buffer' both receive A0-A11 inputs. The 'Row Address Buffer' outputs to the 'Row Decoder', and the 'Col. Address Buffer' outputs to the 'Column Decoder'. The 'Row Decoder' and 'Column Decoder' are connected to the 'Memory Array 16,777,216 x1 Cells'. The 'Sense Amps & I/O' block is connected to the memory array and provides feedback to the 'Refresh Control' and 'Refresh Counter'. The 'Data in Buffer' receives input D and is connected to the 'Row Decoder' and 'Sense Amps & I/O'. The 'Data out Buffer' receives input from the 'Sense Amps & I/O' and outputs Q .

SAMSUNG
ELECTRONICS

PIN CONFIGURATION (Top Views)



Pin Name	Pin Function
A0 - A11	Address Inputs (4K Product)
D	Data In
Q	Data Out
Vss	Ground
RAS	Row Address Strobe
CAS	Column Address Strobe
W	Read/Write Input
Vcc	Power(+5.0V)
	Power(+3.3V)
N.C	No Connection

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating		Units
		3.3V	5V	
Voltage on any pin relative to Vss	V _{IN} , V _{OUT}	-0.5 to +4.6	-1.0 to +7.0	V
Voltage on Vcc supply relative to Vss	V _{CC}	-0.5 to +4.6	-1.0 to +7.0	V
Storage Temperature	T _{stg}	-55 to +150	-55 to +150	°C
Power Dissipation	P _D	1	1	W
Short Circuit Output Current	I _{os}	50	50	mA

* Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS (Voltage referenced to Vss, T_A = 0 to 70°C)

Parameter	Symbol	3.3V			5V			Units
		Min	Typ	Max	Min	Typ	Max	
Supply Voltage	V _{CC}	3.0	3.3	3.6	4.5	5.0	5.5	V
Ground	V _{SS}	0	0	0	0	0	0	V
Input High Voltage	V _{IH}	2.0	-	V _{CC} +0.3* ¹	2.4	-	V _{CC} +1.0* ¹	V
Input Low Voltage	V _{IL}	-0.3* ²	-	0.8	-1.0* ²	-	0.8	V

*1 : V_{CC}+1.3V/15ns(3.3V), V_{CC}+2.0/20ns(5V), Pulse width is measured at V_{CC}

*2 : -1.3V/15ns(3.3V), -2.0/20ns(5V), Pulse width is measured at V_{SS}

DC AND OPERATING CHARACTERISTICS (Recommended operating conditions unless otherwise noted.)

Max	Parameter	Symbol	Min	Max	Units
3.3V	Input Leakage Current (Any input 0≤V _{IN} ≤V _{IN} +0.3V, all other input pins not under test=0 Volt)	I _{I(L)}	-5	5	μA
	Output Leakage Current (Data out is disabled, 0V≤V _{OUT} ≤V _{CC})	I _{O(L)}	-5	5	μA
	Output High Voltage Level(I _{OH} =-2mA)	V _{OH}	2.4	-	V
	Output Low Voltage Level(I _{OL} =2mA)	V _{OL}	-	0.4	V
5V	Input Leakage Current (Any input 0≤V _{IN} ≤V _{IN} +0.5V, all other input pins not under test=0 Volt)	I _{I(L)}	-5	5	μA
	Output Leakage Current (Data out is disabled, 0V≤V _{OUT} ≤V _{CC})	I _{O(L)}	-5	5	μA
	Output High Voltage Level(I _{OH} =-5mA)	V _{OH}	2.4	-	V
	Output Low Voltage Level(I _{OL} =4.2mA)	V _{OL}	-	0.4	V

DC AND OPERATING CHARACTERISTICS (Continued)

Symbol	Power	Speed	Max		Units
			KM41V16000C	KM41C16000C	
I _{CC1}	Don't care	-5	90	90	mA
		-6	80	80	mA
I _{CC2}	Normal L	Don't care	1	2	mA
			1	1	mA
I _{CC3}	Don't care	-5	90	100	mA
		-6	80	90	mA
I _{CC4}	Don't care	-5	90	90	mA
		-6	80	80	mA
I _{CC5}	Normal L	Don't care	0.5	1	mA
			200	250	uA
I _{CC6}	Don't care	-5	90	100	mA
		-6	80	90	mA
I _{CC7}	L	Don't care	200	300	uA
I _{CCS}	L	Don't care	150	250	uA

I_{CC1}* : Operating Current ($\overline{RAS}$ and $\overline{CAS}$ cycling @trc=min.)

I_{CC2} : Standby Current ($\overline{RAS}=\overline{CAS}=\overline{W}=V_{IH}$)

I_{CC3}* : $\overline{RAS}$ -only Refresh Current ($\overline{CAS}=V_{IH}$, $\overline{RAS}$ cycling @trc=min.)

I_{CC4}* : Fast Page Mode Current ($\overline{RAS}=V_{IL}$, $\overline{CAS}$, Address cycling @t_{PC}=min.)

I_{CC5} : Standby Current ($\overline{RAS}=\overline{CAS}=\overline{W}=V_{CC}-0.2V$)

I_{CC6}* : $\overline{CAS}$ -Before- $\overline{RAS}$ Refresh Current ($\overline{RAS}$ and $\overline{CAS}$ cycling @trc=min.)

I_{CC7} : Battery back-up current, Average power supply current, Battery back-up mode

Input high voltage(V_{IH})= $V_{CC}-0.2V$, Input low voltage(V_{IL})=0.2V, $\overline{CAS}=0.2V$,

DQ=Don't care, TRC=31.25us(L-ver), TRAS=TRASmin~300ns

I_{CCS} : Self Refresh Current

$\overline{RAS}=\overline{CAS}=0.2V$, $\overline{W}=A0 \sim A11=V_{CC}-0.2V$ or 0.2V,

D, Q= $V_{CC}-0.2V$, 0.2V or Open

***Note :** I_{CC1}, I_{CC3}, I_{CC4} and I_{CC6} are dependent on output loading and cycle rates. Specified values are obtained with the output open. I_{CC} is specified as an average current. In I_{CC1}, I_{CC3} and I_{CC6} address can be changed maximum once while $\overline{RAS}=V_{IL}$. In I_{CC4}, address can be changed maximum once within one fast page mode cycle time, t_{PC}.

KM41C16000C, KM41V16000C

CMOS DRAM

CAPACITANCE (TA=25°C, VCC=5V or 3.3V, f=1MHz)

Parameter	Symbol	Min	Max	Units
Input capacitance [D]	CIN1	-	7	pF
Input capacitance [A0 ~ A11]	CIN2	-	5	pF
Input capacitance [$\overline{\text{RAS}}$, $\overline{\text{CAS}}$, $\overline{\text{W}}$, $\overline{\text{OE}}$]	CIN3	-	7	pF
Output capacitance [Q]	COUT	-	7	pF

AC CHARACTERISTICS (0°C≤TA≤70°C, See note 1,2)

Test condition (5V device) : VCC=5.0V±10%, Vih/Vil=2.4/0.8V, Voh/Vol=2.4/0.4V

Test condition (3.3V device) : VCC=3.3V±0.3V, Vih/Vil=2.0/0.8V, Voh/Vol=2.0/0.8V

Parameter	Symbol	-5		-6		Units	Notes
		Min	Max	Min	Max		
Random read or write cycle time	tRC	90		110		ns	
Read-modify-write cycle time	tRWC	110		130		ns	
Access time from $\overline{\text{RAS}}$	tRAC		50		60	ns	3,4,10
Access time from $\overline{\text{CAS}}$	tCAC		13		15	ns	3,5
Access time from column address	tAA		25		30	ns	3,10
$\overline{\text{CAS}}$ to output in Low-Z	tCLZ	0		0		ns	3
Output buffer turn-off delay	tOFF	0	13	0	15	ns	6
Transition time (rise and fall)	tT	3	50	3	50	ns	2
$\overline{\text{RAS}}$ precharge time	tRP	30		40		ns	
$\overline{\text{RAS}}$ pulse width	tRAS	50	10K	60	10K	ns	
$\overline{\text{RAS}}$ hold time	tRSH	13		15		ns	
$\overline{\text{CAS}}$ hold time	tCSH	50		60		ns	
$\overline{\text{CAS}}$ pulse width	tCAS	13	10K	15	10K	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	tRCD	20	37	20	45	ns	4
$\overline{\text{RAS}}$ to column address delay time	tRAD	15	25	15	30	ns	10
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ precharge time	tCRP	5		5		ns	
Row address set-up time	tASR	0		0		ns	
Row address hold time	tRAH	10		10		ns	
Column address set-up time	tASC	0		0		ns	
Column address hold time	tCAH	10		10		ns	
Column address to $\overline{\text{RAS}}$ lead time	tRAL	25		30		ns	
Read command set-up time	tRCS	0		0		ns	
Read command hold time referenced to $\overline{\text{CAS}}$	tRCH	0		0		ns	8
Read command hold time referenced to $\overline{\text{RAS}}$	tRRH	0		0		ns	8
Write command hold time	tWCH	10		10		ns	
Write command pulse width	tWP	10		10		ns	
Write command to $\overline{\text{RAS}}$ lead time	tRWL	13		15		ns	
Write command to $\overline{\text{CAS}}$ lead time	tCWL	13		15		ns	

AC CHARACTERISTICS (Continued)

Parameter	Symbol	-5		-6		Units	Notes
		Min	Max	Min	Max		
Data set-up time	t _{DS}	0		0		ns	9
Data hold time	t _{DH}	10		10		ns	9
Refresh period (Normal)	t _{REF}		64		64	ms	
Refresh period (L-ver)	t _{REF}		128		128	ms	
Write command set-up time	t _{WCS}	0		0		ns	7
$\overline{\text{CAS}}$ to $\overline{\text{W}}$ delay time	t _{CWD}	13		15		ns	7
$\overline{\text{RAS}}$ to $\overline{\text{W}}$ delay time	t _{RWD}	50		60		ns	7
Column address to $\overline{\text{W}}$ delay time	t _{AWD}	25		30		ns	7
$\overline{\text{CAS}}$ precharge to $\overline{\text{W}}$ delay time	t _{CPWD}	30		35		ns	
$\overline{\text{CAS}}$ set-up time ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh)	t _{CSR}	5		5		ns	
$\overline{\text{CAS}}$ hold time ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh)	t _{CHR}	10		10		ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ precharge time	t _{RPC}	5		5		ns	
Access time from $\overline{\text{CAS}}$ precharge	t _{CPA}		30		35	ns	3
Fast Page mode cycle time	t _{PC}	35		40		ns	
Fast Page read-modify-write cycle time	t _{PRWC}	53		60		ns	
$\overline{\text{CAS}}$ precharge time (Fast Page cycle)	t _{CP}	10		10		ns	
$\overline{\text{RAS}}$ pulse width (Fast Page cycle)	t _{RASP}	50	200K	60	200K	ns	
$\overline{\text{RAS}}$ hold time from $\overline{\text{CAS}}$ precharge	t _{RHCP}	30		35		ns	
Write command set-up time (Test mode in)	t _{WTS}	10		10		ns	11
Write command hold time (Test mode in)	t _{WTH}	10		10		ns	11
$\overline{\text{W}}$ to $\overline{\text{RAS}}$ precharge time($\overline{\text{C}}$ -B- $\overline{\text{R}}$ refresh)	t _{WRP}	10		10		ns	
$\overline{\text{W}}$ to $\overline{\text{RAS}}$ hold time($\overline{\text{C}}$ -B- $\overline{\text{R}}$ refresh)	t _{WRH}	10		10		ns	
$\overline{\text{RAS}}$ pulse width ($\overline{\text{C}}$ -B- $\overline{\text{R}}$ self refresh)	t _{RASS}	100		100		us	13,14,15
$\overline{\text{RAS}}$ precharge time ($\overline{\text{C}}$ -B- $\overline{\text{R}}$ self refresh)	t _{RPS}	90		110		ns	13,14,15
$\overline{\text{CAS}}$ hold time ($\overline{\text{C}}$ -B- $\overline{\text{R}}$ self refresh)	t _{CHS}	-50		-50		ns	13,14,15

TEST MODE CYCLE

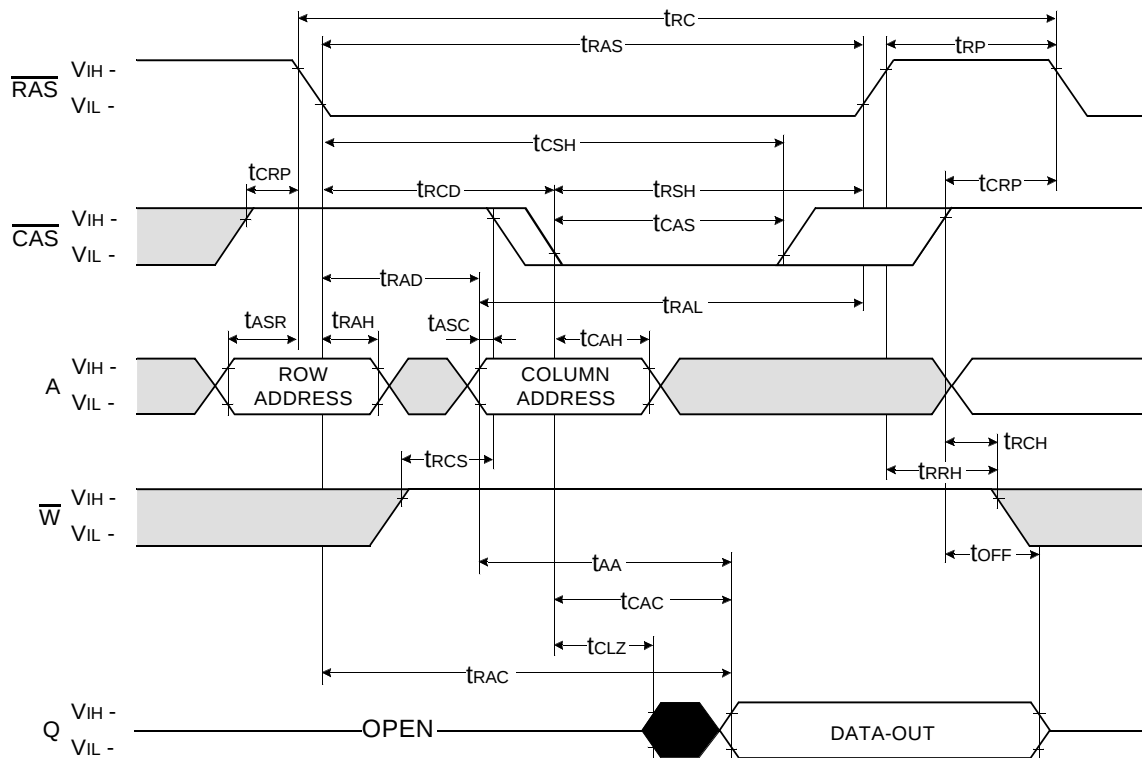
(Note 11)

Parameter	Symbol	-5		-6		Units	Notes
		Min	Max	Min	Max		
Random read or write cycle time	t _{RC}	95		115		ns	
Read-modify-write cycle time	t _{RWC}	115		135		ns	
Access time from $\overline{\text{RAS}}$	t _{RAC}		55		65	ns	3,4,10,12
Access time from $\overline{\text{CAS}}$	t _{CAC}		18		20	ns	3,5,12
Access time from column address	t _{AA}		30		35	ns	3,10,12
$\overline{\text{RAS}}$ pulse width	t _{RAS}	55	10K	65	10K	ns	
$\overline{\text{CAS}}$ pulse width	t _{CAS}	18	10K	20	10K	ns	
$\overline{\text{RAS}}$ hold time	t _{RSH}	18		20		ns	
$\overline{\text{CAS}}$ hold time	t _{CSH}	55		65		ns	
Column address to $\overline{\text{RAS}}$ lead time	t _{RAL}	30		35		ns	
$\overline{\text{CAS}}$ to $\overline{\text{W}}$ delay time	t _{CWD}	18		20		ns	7
$\overline{\text{RAS}}$ to $\overline{\text{W}}$ delay time	t _{RWD}	55		65		ns	7
Column address to $\overline{\text{W}}$ delay time	t _{AWD}	30		35		ns	7
$\overline{\text{CAS}}$ precharge to $\overline{\text{W}}$ delay time	t _{CPWD}	35		40		ns	
Fast Page mode cycle time	t _{PC}	40		45		ns	
Fast Page read-modify-write cycle time	t _{PRWC}	58		65		ns	
$\overline{\text{RAS}}$ pulse width (Fast Page cycle)	t _{RASP}	55	200K	65	200K	ns	
Access time from $\overline{\text{CAS}}$ precharge	t _{CPA}		35		40	ns	3

NOTES

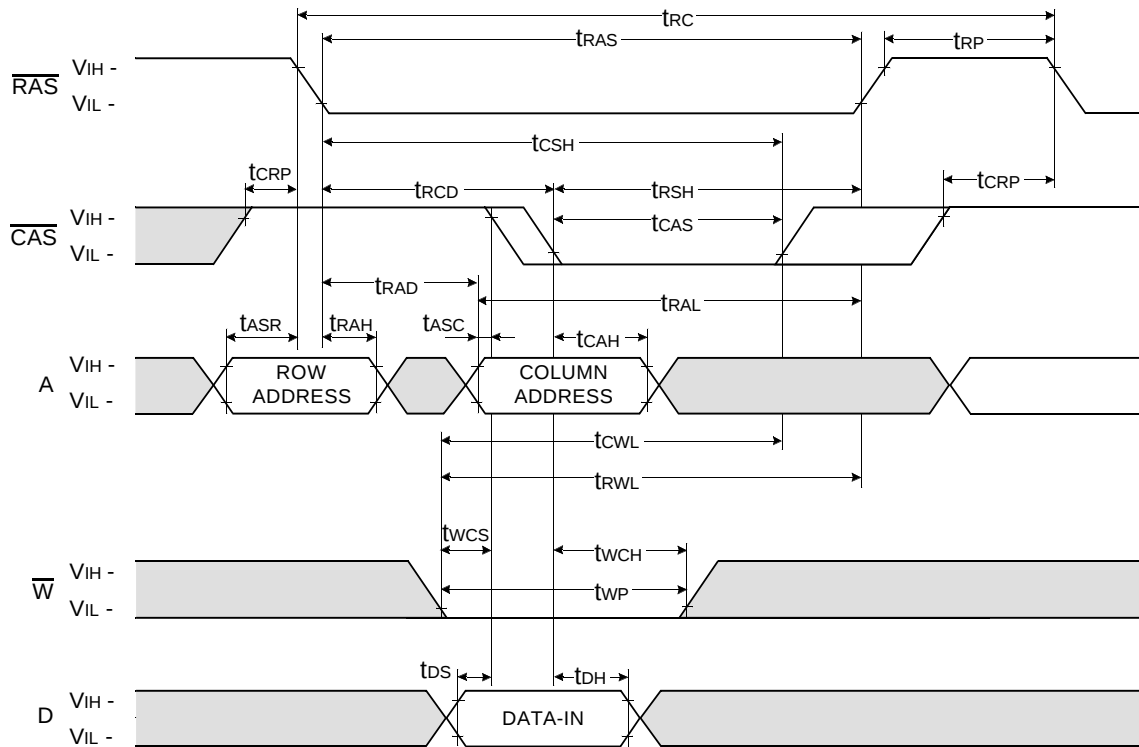
1. An initial pause of 200us is required after power-up followed by any 8 $\overline{\text{RAS}}$ -only refresh or $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycles before proper device operation is achieved.
2. $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ are reference levels for measuring timing of input signals. Transition times are measured between $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ and are assumed to be 5ns for all inputs.
3. Measured with a load equivalent to 2 TTL(5V)/1 TTL(3.3V) loads and 100pF.
4. Operation within the $t_{\text{RCD}}(\text{max})$ limit insures that $t_{\text{RAC}}(\text{max})$ can be met. $t_{\text{RCD}}(\text{max})$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{\text{RCD}}(\text{max})$ limit, then access time is controlled exclusively by t_{CAC} .
5. Assumes that $t_{\text{RCD}} \geq t_{\text{RCD}}(\text{max})$.
6. $t_{\text{OFF}}(\text{min})$ and $t_{\text{OEZ}}(\text{max})$ define the time at which the output achieves the open circuit condition and are not referenced V_{OH} or V_{OL} .
7. t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are non restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If $t_{\text{WCS}} \geq t_{\text{WCS}}(\text{min})$, the cycle is an early write cycle and the data output will remain high impedance for the duration of the cycle. If $t_{\text{CWD}} \geq t_{\text{CWD}}(\text{min})$, $t_{\text{RWD}} \geq t_{\text{RWD}}(\text{min})$ and $t_{\text{AWD}} \geq t_{\text{AWD}}(\text{min})$, then the cycle is a read-modify-write cycle and the data output will contain the data read from the selected address. If neither of the above conditions is satisfied, the condition of the data out is indeterminate.
8. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
9. These parameters are referenced to $\overline{\text{CAS}}$ falling edge in early write cycles and to $\overline{W}$ falling edge in read-modify-write cycles.
10. Operation within the $t_{\text{RAD}}(\text{max})$ limit insures that $t_{\text{RAC}}(\text{max})$ can be met. $t_{\text{RAD}}(\text{max})$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{\text{RAD}}(\text{max})$ limit, then access time is controlled by t_{AA} .
11. These specifications are applied in the test mode.
12. In test mode read cycle, the value of t_{RAC} , t_{AA} , t_{CAC} is delayed by 2ns to 5ns for the specified values. These parameters should be specified in test mode cycles by adding the above value to the specified value in this data sheet.
13. If $t_{\text{RASS}} \geq 100\mu\text{s}$, then $\overline{\text{RAS}}$ precharge time must use t_{RPS} instead of t_{RP} .
14. For $\overline{\text{RAS}}$ -only refresh and burst $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh mode, 4096(4K) cycles of burst refresh must be executed within 64ms before and after self refresh, in order to meet refresh specification.
15. For distributed $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ with 15.6us interval $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh should be executed with in 15.6us immediately before and after self refresh in order to meet refresh specification.

READ CYCLE



Don't care
Undefined

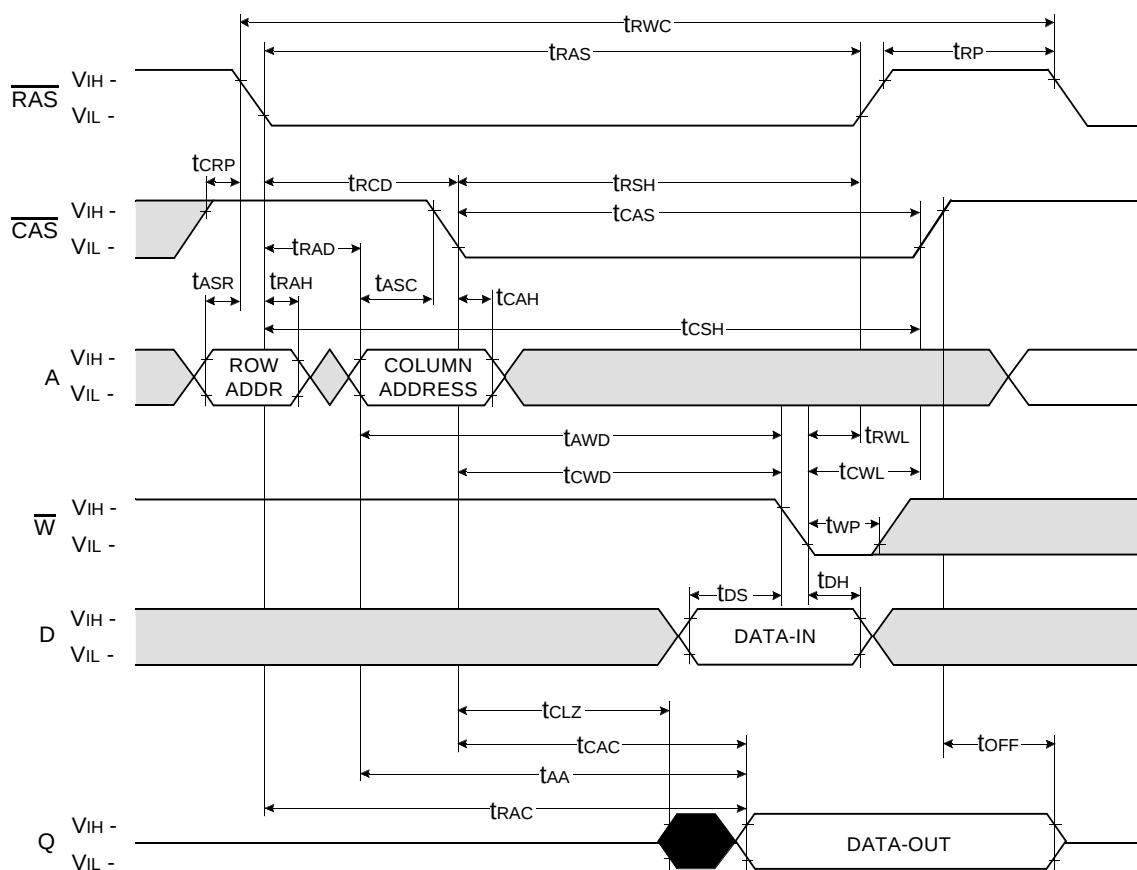
WRITE CYCLE (EARLY WRITE)



Don't care

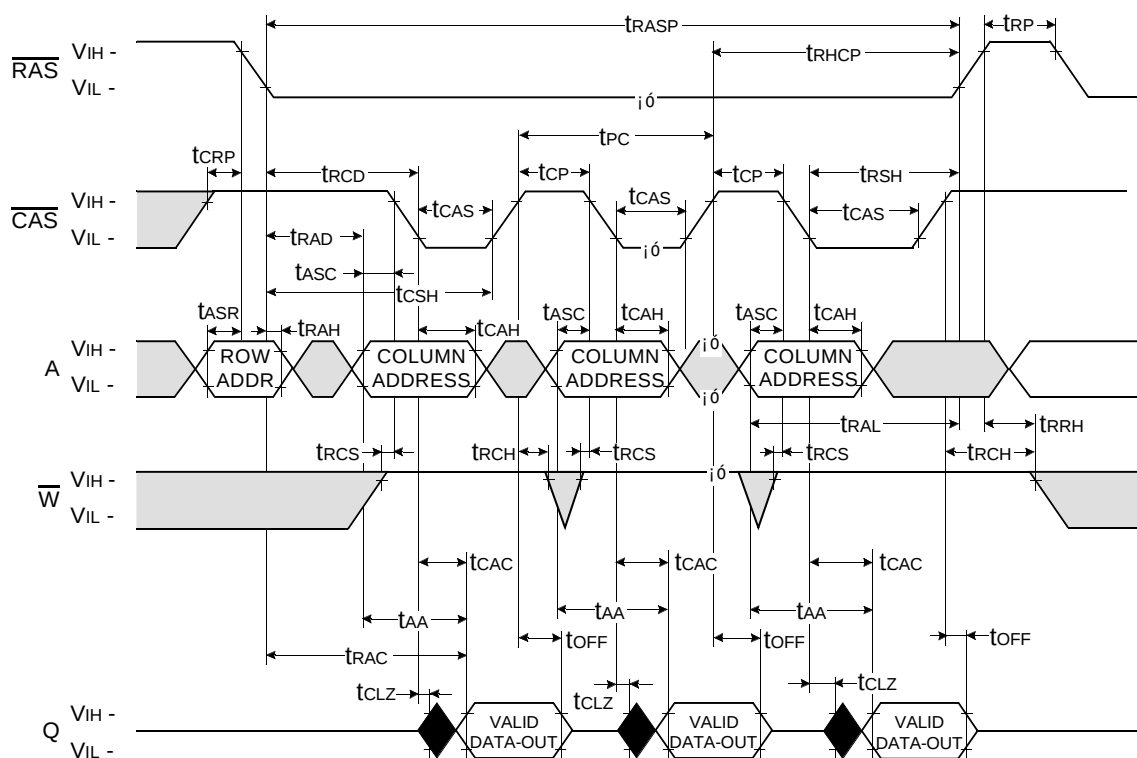
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READ-WRITE / READ - MODIFY - WRITE CYCLE



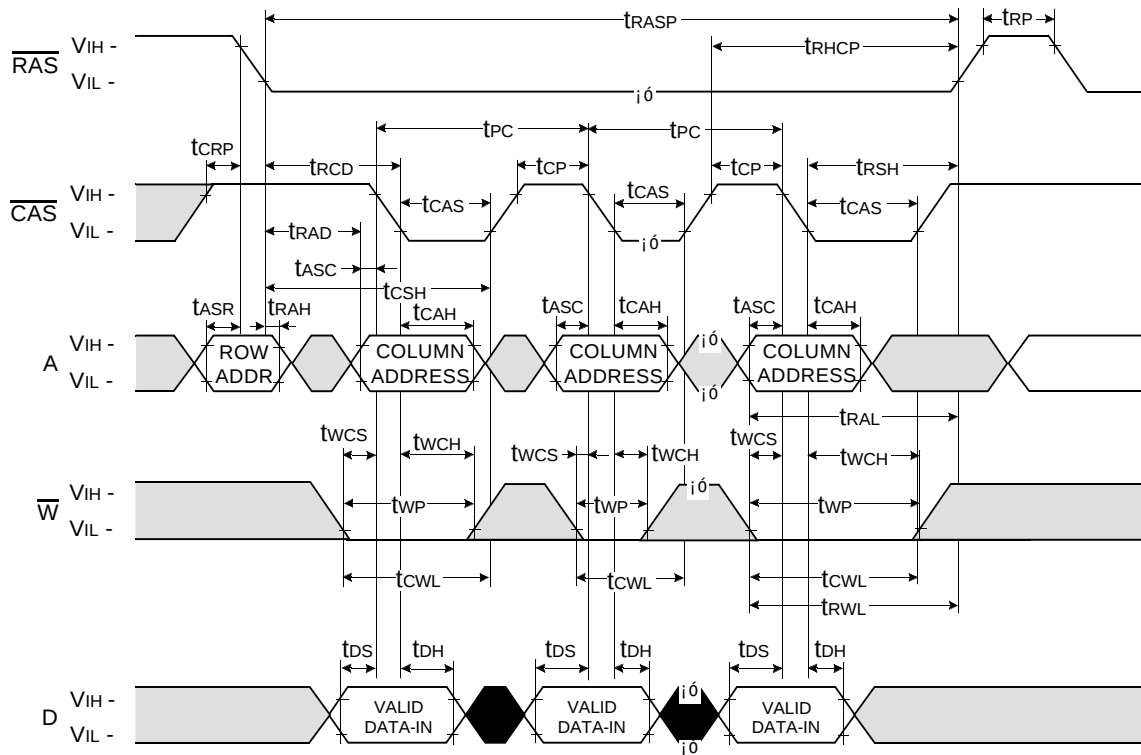
Don't care
Undefined

FAST PAGE READ CYCLE

☐ Don't care

Undefined

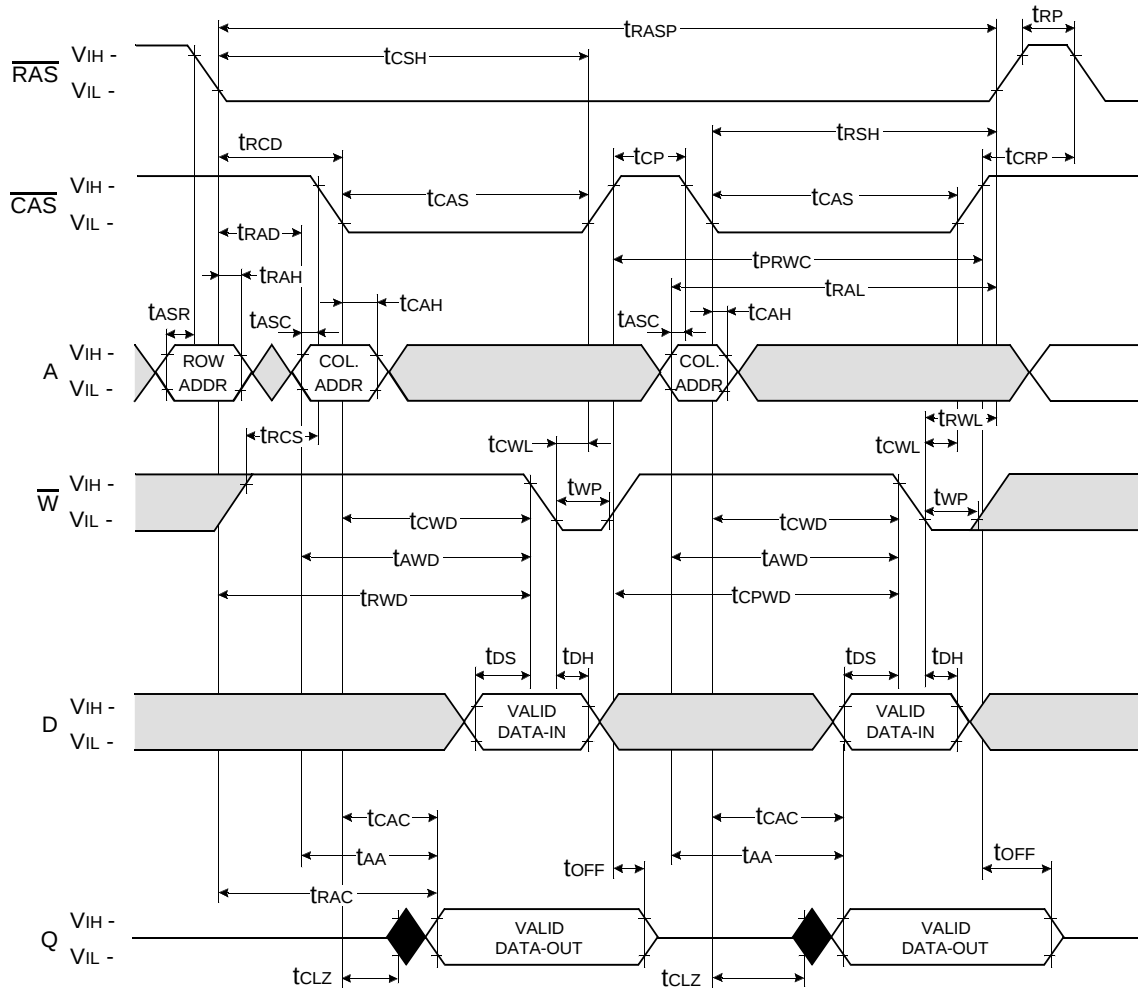
FAST PAGE WRITE CYCLE (EARLY WRITE)



Don't care

Undefined

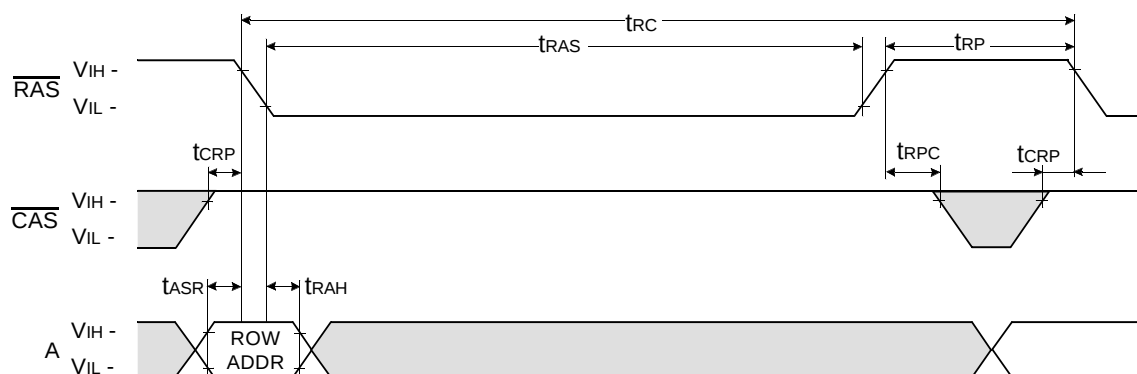
FAST PAGE READ - MODIFY - WRITE CYCLE



$\overline{\text{RAS}}$ - ONLY REFRESH CYCLE

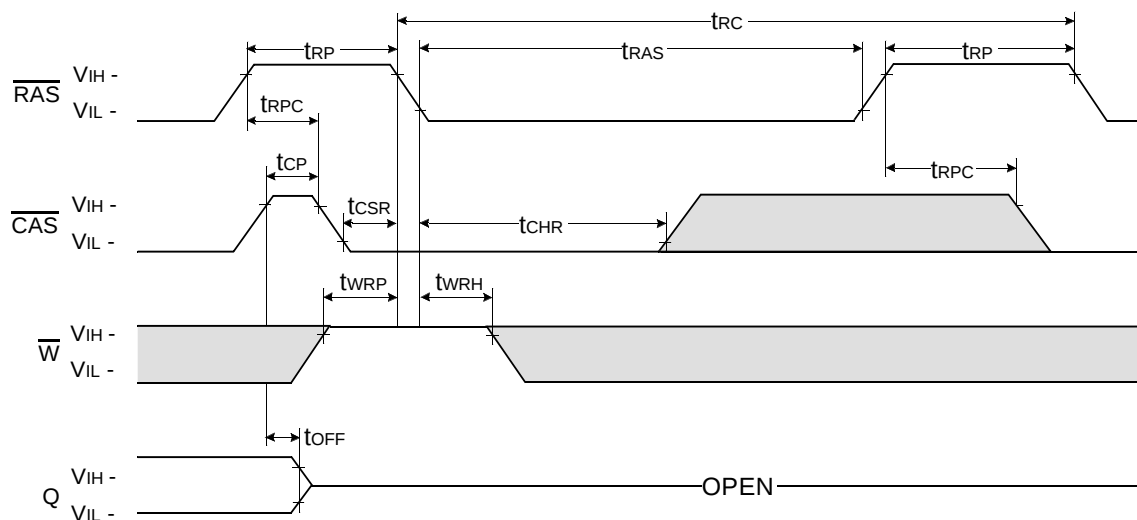
NOTE : $\overline{\text{W}}$, DIN = Don't care

DOUT = OPEN



$\overline{\text{CAS}}$ - BEFORE - $\overline{\text{RAS}}$ REFRESH CYCLE

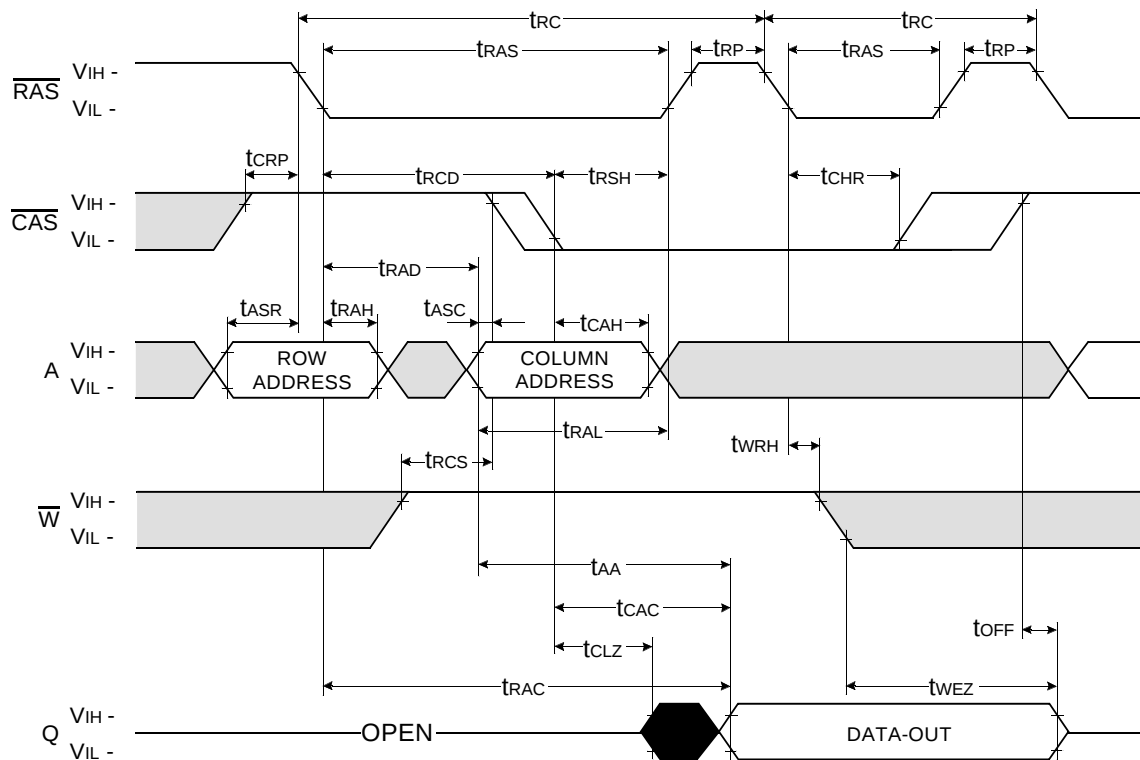
NOTE : A = Don't care



Don't care

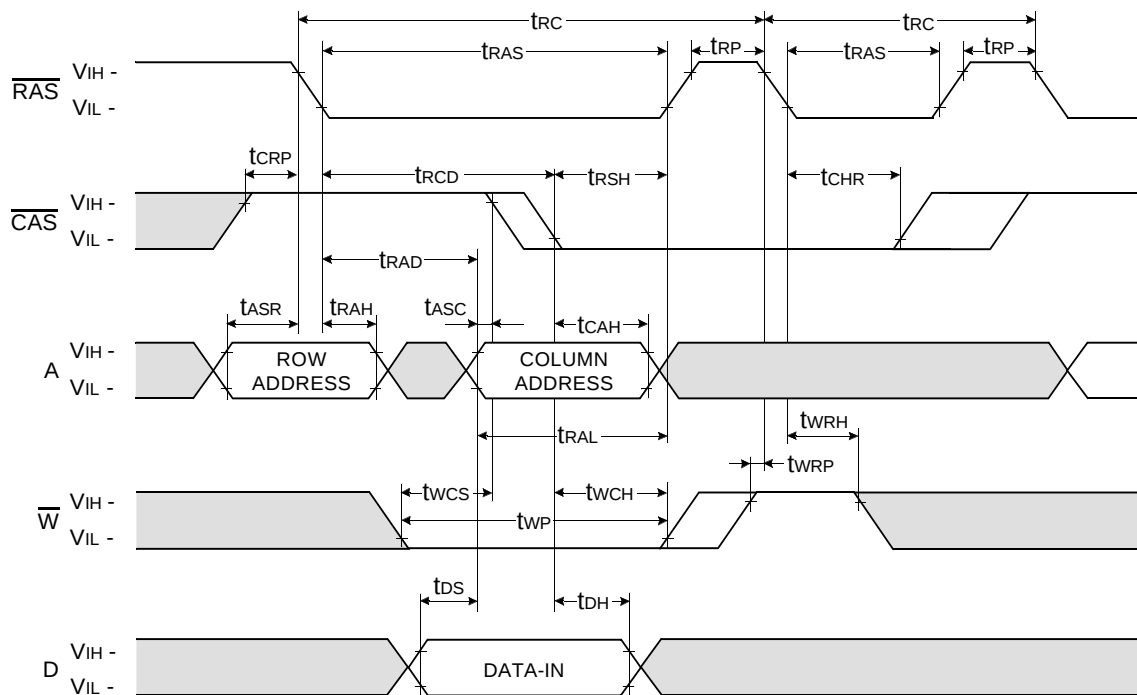
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HIDDEN REFRESH CYCLE (READ)



HIDDEN REFRESH CYCLE (WRITE)

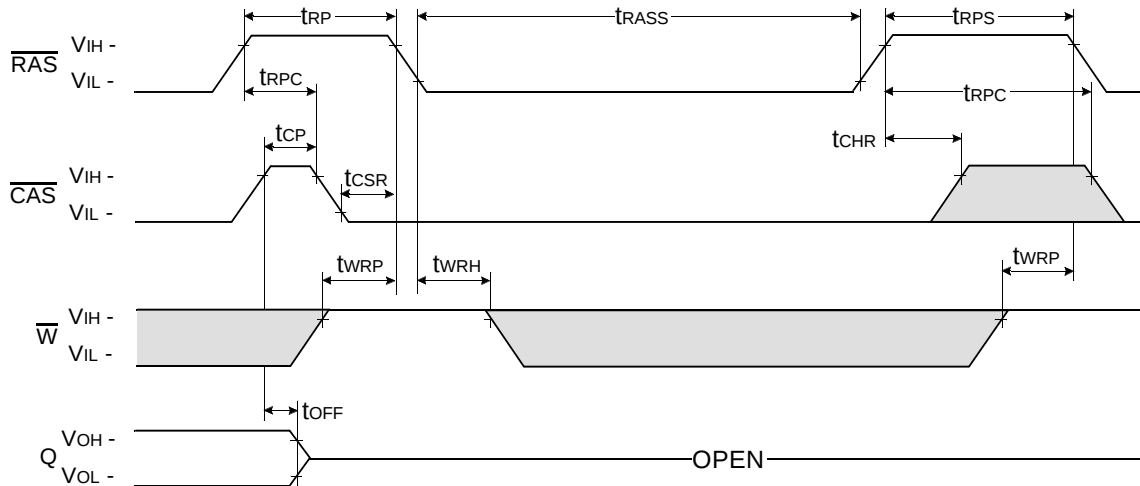
NOTE : DOUT = OPEN



Don't care
Undefined

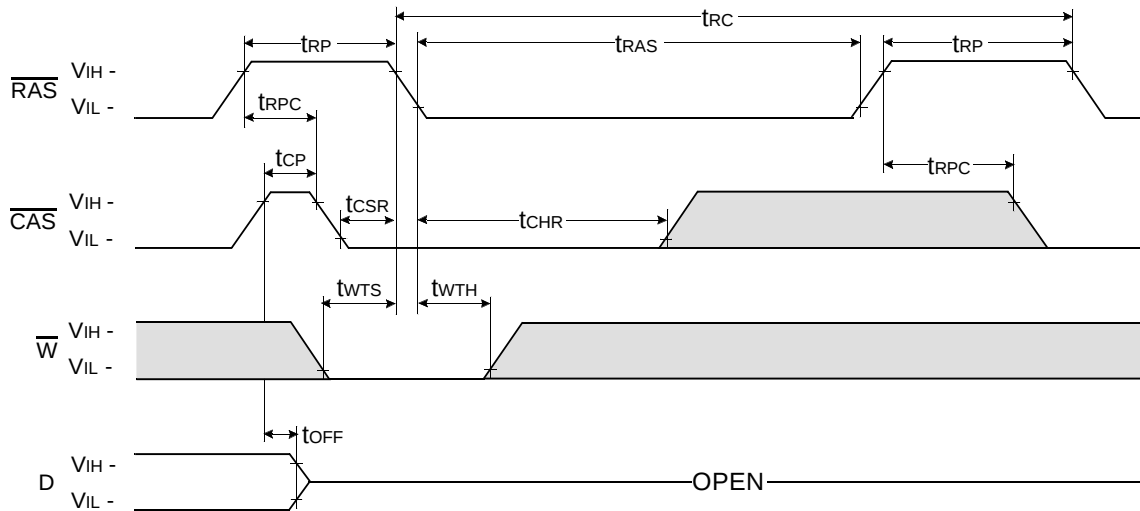
$\overline{\text{CAS}}$ - BEFORE - $\overline{\text{RAS}}$ SELF REFRESH CYCLE

NOTE : A = Don't care



TEST MODE IN CYCLE

NOTE : D, A = Don't care

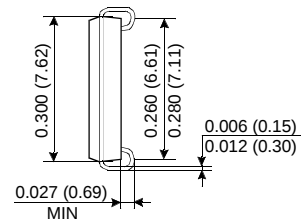
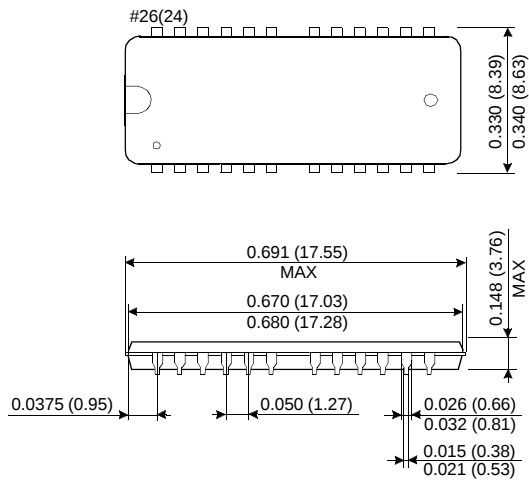


Don't care
Undefined

PACKAGE DIMENSION

26(24) SOJ 300mil

Units : Inches (millimeters)



26(24) TSOP(II) 300mil

Units : Inches (millimeters)

